

S29NS512R

CS Q99023

Qualification of: S29NS512R, 512 Megabit (32M x 16 bit), 1.8 Volt-only, Multiplexed Simultaneous Read/Write Burst Mode Flash Memory in VDH064 (8 x 9.2 x 1mm) 64 Ball, Very Thin Fine Pitch Ball Grid Array Package (vFBGA)



Reliability Qualification Summary

CONFIDENTIAL

NOTICE: The material in this report is confidential. It is prepared to assist in the qualification of our product. It is declassified for the internal use of our customers only, and may be modified to meet the needs of specific customers. It also serves as a record of full qualification according to JESD47 and AEC-Q100 Grade 1 requirements.

Additionally, the package details (material set, assembly location, etc.) are specific to the qual vehicle used for the qualification. Alternate material sets and assembly locations may be qualified for the product. Production material can be assembled with any qualified material set and at any qualified assembly location. Tests are performed in accordance with AEC-Q100 and relevant JEDEC specifications.

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I. Product Information

Product Description: S29NS512R
 512 Megabit (32M x 16 bit), 1.8 Volt-only, Multiplexed Simultaneous Read/Write Burst Mode Flash Memory

Package:	VDH064	Qualification:	Q99023
Description:	(8 x 9.2 x 1mm) 64 Ball, Very Thin Fine Pitch Ball Grid Array Package (vFBGA)		
Theta Ja:	39 °C/W	Psi Jt:	11 °C/W
Assembly Location:	Spansion Thailand	Molding Compound:	RoHS Compliant Epoxy Resin
Substrate/Leadframe:	BT Resin Substrate	Die Attachment:	Paste
Lead Finish:	98.3Sn1.2Ag0.5Cu Spheres	Bond Wire:	Gold
Comments:			

Est. Field Temperature:	55 °C	Life Test Temperature:	150 °C
Est. DC Field Current:	50 mA	Life Test Dynamic Current:	10 mA
Est. Field Voltage:	1.8 V	Life Test Voltage:	1.95 V
Est. Field Power Dissipation:	90 mWatts	Est. Stress Power Dissipation:	19.5 mWatts
Est. Field Tj:	58.5 °C	Est. Stress Tj:	150.7 °C

Die:	98Y06B	Die Size:	5.10 x 7.29 mm
Process:	CS239AL (65nm)	Fab:	Spansion SP1
Type:	MirrorBit	Density:	512M

II. CS239/L Life Test Failure Rate Calculation

HTOL Stress Temperature - 125 °C

Failure Mechanism	Read Points / Test Results				Modeling Parameters @ 55°C					Avg. Failure Rate FITS @ 55°C, 60% Conf.	
	24 hrs	168 hrs	1000 hrs	2000 hrs	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life	Inherent Life
PLASTIC											
Sample Size	3882	3880	540	100							
Zero fails, Process ave. Ea	0 *	0	0	0	0.66	41	1	41		59	19
Totals	0	0	0	0					6008	59	19

* Contributes to early life FITS

Data Retention Bake - 150 °C

Reliability Stress	Number of Rejects	Sample Size	Failure Rate %	Failure Mechanism
500 hrs	0	1200	0.00	No Failures
1000 hrs	0	1098	0.00	No Failures

III. Summary of Stress Test Results

Stress Test	Stress Condition	Package Type	Sample Size	Num. of Lots	Num. of Fails	Failure Rate %	Comments
Data From Qualification Q99023:							
HTOL (EL)	(1.95V, 150°C)	VDH064 ¹	79	1	0	0.00	168 hours
Data Retention Bake	(150°C)	VDH064 ¹	77	1	0	0.00	84 hours
ESD CDM	N/A	VDH064 ¹	30	2	Passed	1.0kV	
ESD HBM	(100pF, 1500 Ohms)	VDH064 ¹	312	2	Passed	2.0kV	
Latch Up	(125°C, +/- 100mA)	VDH064 ¹	6	1	Passed		
Endurance (10k)	(-25°C, 1.7V)	VDH064 ¹	48	1	0	0.00	10k cycles
	(-25°C, 1.95V)	VDH064 ¹	48	1	0	0.00	10k cycles
	(90°C, 1.7V)	VDH064 ¹	48	1	0	0.00	10k cycles
	(90°C, 1.95V)	VDH064 ¹	48	1	0	0.00	10k cycles
Preconditioning	(PC1/260°C, +0°C/-5°C)	VDH064 ¹	231	2	Passed	Jedec L3 / Jeita Rank E	
Precon+Temp Cycle	(PC1/260°C, -40°C/150°C)	VDH064 ¹	77	1	0	0.00	500 cycles
Precon+HAST	(PC1/260°C, Biased, 110°C/85% RH)	VDH064 ¹	77	2	0	0.00	96 hours
Precon+uHAST	(PC1/260°C, Unbiased, 130°C/85% RH)	VDH064 ¹	77	2	0	0.00	96 hours

Notes / Justification: 1) Results from Qual Q99023, S29NS512R, 512M CS239AL (65nm) MirrorBit in 64 Ball vFBGA (8 x 9.2 x 1mm)

Preconditioning Flows: PC1 (Exceeds JEDEC L3 and JEITA Rank E): Bake 125°C, 24hr => Soak @ 30°C/70%RH, 216hr => 3x Reflow

IV. Revision History

Section	Description
Revision A - 3/4/2008	Initial Release.

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